

DC Input 16-Pin DMC® Half Pitch Mini-Flat Phototransistor Optocoupler

Features

- High isolation 3750 V_{RMS}
- Patented coplanar structure DMC®
- Various CTR selection available
- DC input with transistor output
- Operating temperature range 55 °C to 125 °C
- RoHS and REACH compliance
- Halogen Free compliance
- Regulatory Approvals
 - ✓ UL UL1577 (pending approval)
 - ✓ VDE EN60747-5-5 (VDE0884-5)
 - ✓ CQC GB4943.1, GB8898

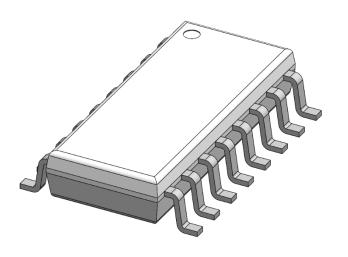
Description

The CTH291-4 series have four isolated channels, each channel contains a photo transistor optically coupled to a gallium arsenide Infrared-emitting diode in a 16-lead **DMC**® half pitch Mini-Flat package.

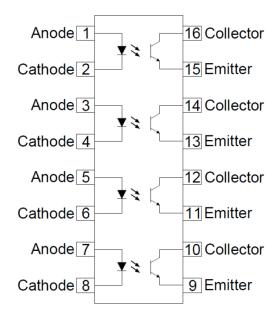
Applications

- DC-DC Converters
- Programmable controllers
- Telecommunication equipment
- Hybrid substrates that require high density mounting

Package Outline



Schematic





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Absolute Maximum Rating at 25°C

| Symbol | Parameters | Ratings | Units | Notes |
|-----------------------|--|------------|------------------|-------|
| Viso | Isolation voltage | 3750 | V _{RMS} | 1 |
| Topr | Operating temperature | -55 ~ +125 | °C | |
| T _{STG} | Storage temperature | -55 ~ +150 | °C | |
| TsoL | Soldering temperature | 260 | °C | 2 |
| Ртот | Total power dissipation | 200 | mW | |
| Emitter | | | | |
| lF | Forward current | 50 | mA | 3 |
| I _{F(TRANS)} | Peak transient current (≤1µs P.W,300pps) | 1 | А | 3 |
| V _R | Reverse voltage | 6 | V | 3 |
| P _D | Power dissipation | 70 | mW | 3 |
| Detector | | | | |
| Pc | Power dissipation | 100 | mW | 3 |
| B _{VCEO} | Collector-Emitter Breakdown Voltage | 80 | V | 3 |
| B _{VECO} | Emitter-Collector Breakdown Voltage | 7 | V | 3 |
| Ic | Collector Current | 50 | mA | 3 |

Notes

- 1. AC for 1 minute, $RH = 40 \sim 60\%$.
- 2. For reflow process
- 3. Each Channel



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Electrical Characteristics $T_A = 25$ °C, Each Channel (unless otherwise specified)

Emitter Characteristics

| Symbol | Parameters | Test Conditions | Min | Тур | Max | Units | Notes |
|-----------------|-------------------|----------------------|-----|------|-----|-------|-------|
| VF | Forward voltage | I _F =10mA | | 1.24 | 1.4 | V | |
| I _R | Reverse Current | V _R = 6V | - | | 5 | μΑ | |
| C _{IN} | Input Capacitance | f= 1MHz | - | 10 | 30 | pF | |

Detector Characteristics

| Symbol | Parameters | Test Conditions | Min | Тур | Max | Units | Notes |
|------------------|--------------------------------|--|-----|-----|-----|-------|-------|
| Bvceo | Collector-Emitter Breakdown | I _C = 0.1mA | 80 | - | - | V | |
| Bveco | Emitter-Collector Breakdown | I _E = 0.1mA | 7 | - | - | V | |
| I _{CEO} | Collector-Emitter Dark Current | V _{CE} = 20V, I _F =0mA | - | - | 100 | nA | |

Transfer Characteristics

| Symbol | Parameters | | Test Conditions | Min | Тур | Max | Units | Notes |
|----------------------|------------------------------|------------|---|--------------------|-----|-----|-------|-------|
| CTR | Current Transfer | CTH291-4 | I _F = 5mA, V _{CE} = 5V | 50 | | 400 | % | |
| CIK | Ratio | CTH291-4GB | IF= SITIA, VCE= SV | 100 | | 400 | 70 | |
| V | Collector-Emitter Saturation | | 1 20m A 1 4m A | | 0.4 | 0.0 | | |
| V _{CE(SAT)} | Voltage | | I _F = 20mA, I _C = 1mA | - | 0.1 | 0.2 | V | |
| Rıo | Isolation Resistance | | V _{IO} = 500V _{DC} | 5x10 ¹⁰ | | | Ω | |
| Cıo | Isolation Capacitance | | f= 1MHz | | 0.5 | 1 | pF | |

Switching Characteristics

| Symbol | Parameters | Test Conditions | Min | Тур | Max | Units | Notes |
|----------------|------------|--|-----|-----|-----|-------|-------|
| t _r | Rise Time | L 0 A V 0V D 4000 | | 6 | 18 | | |
| t _f | Fall Time | Ic= 2mA, V _{CE} = 2V, R _L = 100Ω | • | 8 | 18 | μS | |



Test Circuit

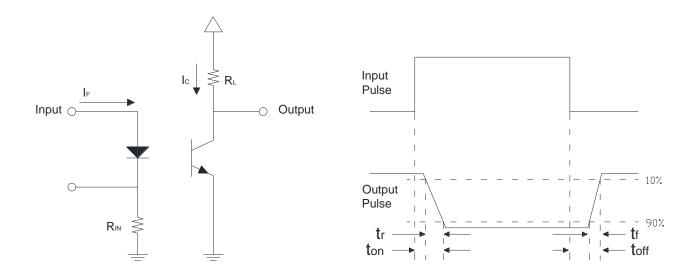
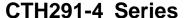
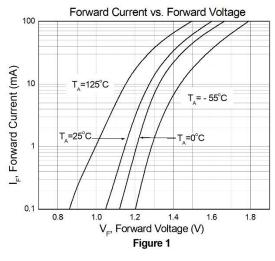


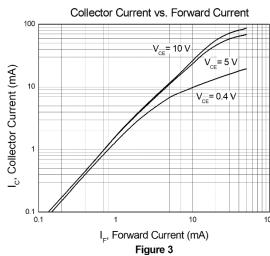
Figure 11: Switching Time Test Circuits

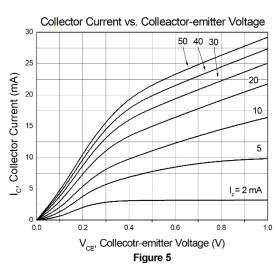


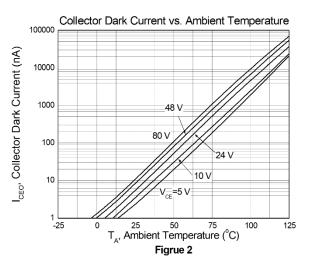


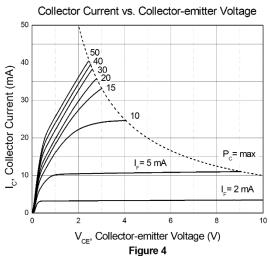
Typical Characteristic Curves

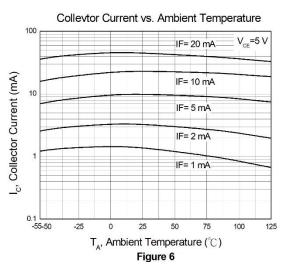






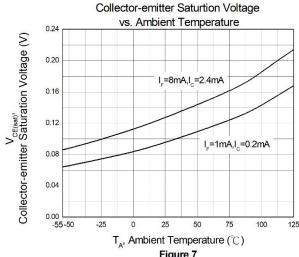


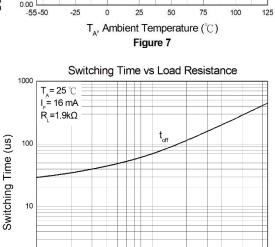




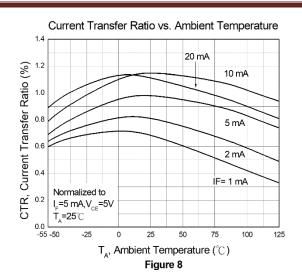


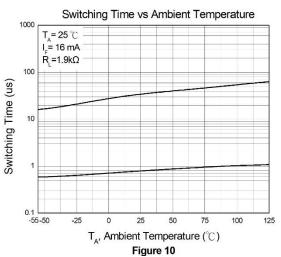
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 R_L , Load Resistance (k Ω) Figure 9

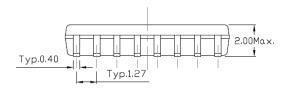


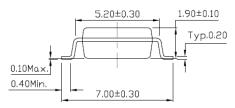


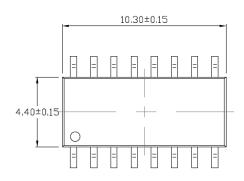


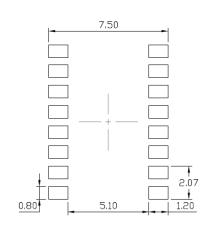
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Package Dimension Dimensions in mm unless otherwise stated









Marking Information



Note:

CT : Denotes "CT Micro"

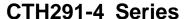
291-4 : Product Number

X : CTR Rank

V : VDE Safety Mark

Y : Fiscal Year WW : Work Week

K : Manufacturing Code





Ordering Information

CTH291-4X (V)(Z)

CT = Denotes "CT Micro"

H291-4 = Product Number

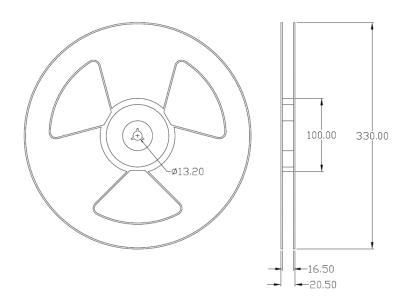
X = CTR Rank Option (Blank or GB)

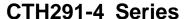
V = VDE Safety Mark Option (Blank or V)

Z = Tape and reel Option (T1 or T2)

| Option Description | | Quantity |
|--------------------|--|-----------------|
| T1 | T1 Surface Mount Lead Forming – With Option 1 Taping | |
| T2 | Surface Mount Lead Forming – With Option 1 Taping | 2000 Units/Reel |

Reel Dimension All dimensions are in mm, unless otherwise stated

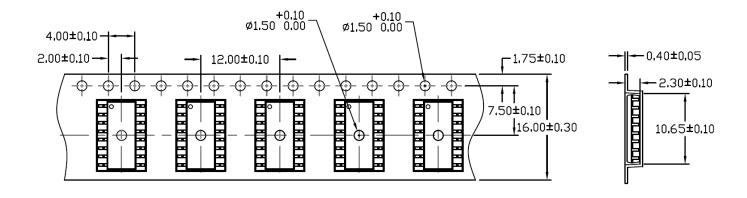




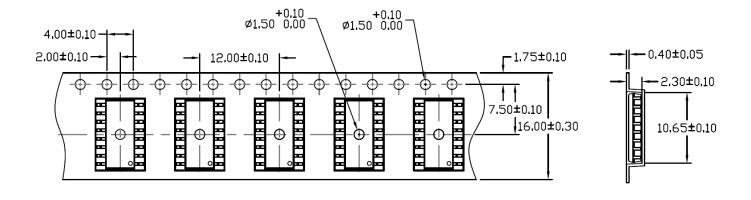


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option T1



Option T2





Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

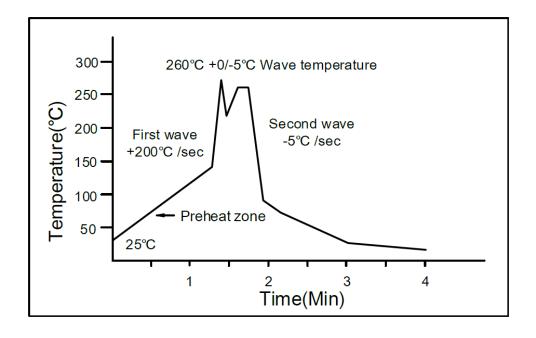
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



Hand soldering by soldering iron (Follow the standard MIL-STD 202G, Method 210F)

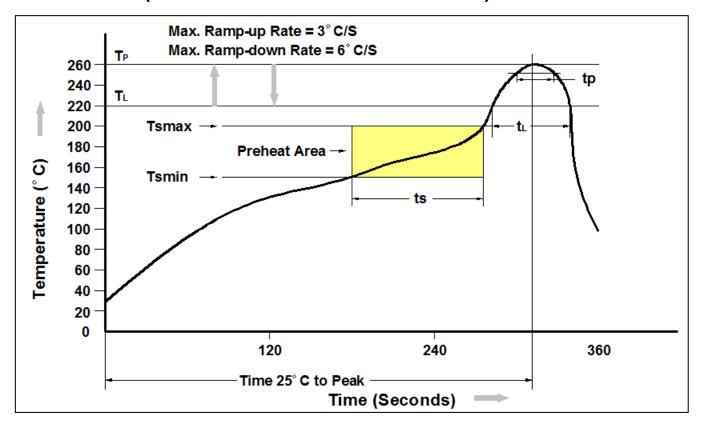
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350±10°C

Time: 5 sec max.



Reflow Profile (follow the JEDEC standard J-STD-020)



| Profile Feature | Pb-Free Assembly Profile |
|---|--------------------------|
| Temperature Min. (Tsmin) | 150°C |
| Temperature Max. (Tsmax) | 200°C |
| Time (ts) from (Tsmin to Tsmax) | 60-120 seconds |
| Ramp-up Rate (t∟ to t₂) | 3°C/second max. |
| Liquidous Temperature (T _L) | 217°C |
| Time (t _L) Maintained Above (T _L) | 60 – 150 seconds |
| Peak Body Package Temperature | 260°C +0°C / -5°C |
| Time (t _P) within 5°C of 260°C | 30 seconds |
| Ramp-down Rate (T _P to T _L) | 6°C/second max |
| Time 25°C to Peak Temperature | 8 minutes max. |



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